

HSM126S

Silicon Schottky Barrier Diode for System Protection

HITACHI

ADE-208-111C (Z)

Rev. 3

May 1995

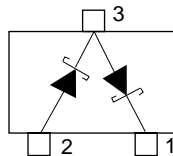
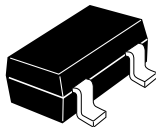
Features

- HSM126S which is connected in series configuration enable to protect electric systems from mis-operation against external + and – surge.
- Low V_F and low leakage current.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM126S	S14	MPAK

Pin Arrangement



(Top View)

- 1 Cathode 2
- 2 Anode 1
- 3 Cathode 1
Anode 2

Absolute Maximum Ratings (Ta = 25°C)*3

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	20	V
Average forward current	I_O^{*1}	200	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*2}	2	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. Sine wave, Two device total
 2. 50Hz half sine wave 1 pulse
 3. Per one device

Electrical Characteristics (Ta = 25°C)*

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	2.0	μA	$V_R = 5V$
Forward voltage	V_F	—	—	0.35	V	$I_F = 10mA$
Capacitance	C	—	40	—	pF	$V_R = 0V, f = 1MHz$

Note: Per one device

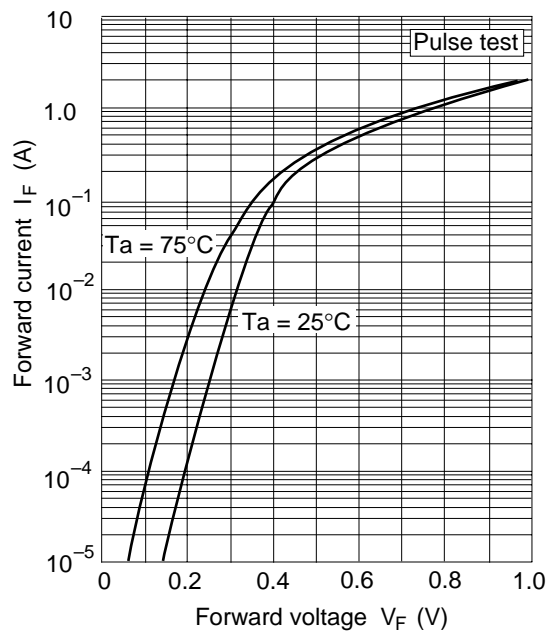


Fig.1 Forward current Vs. Forward voltage

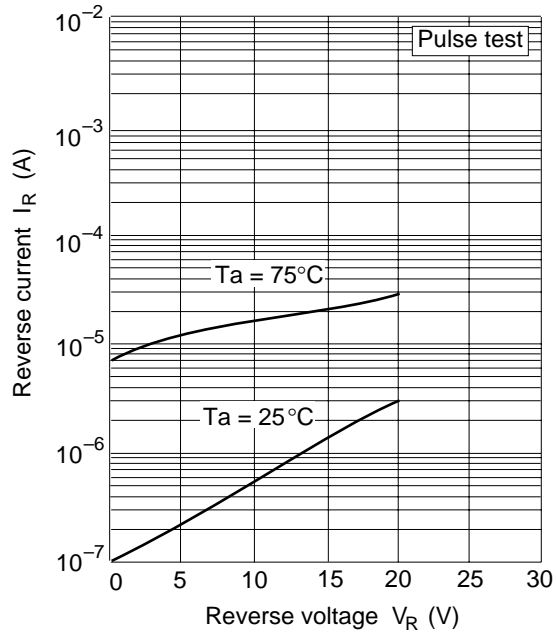


Fig.2 Reverse current Vs. Reverse voltage

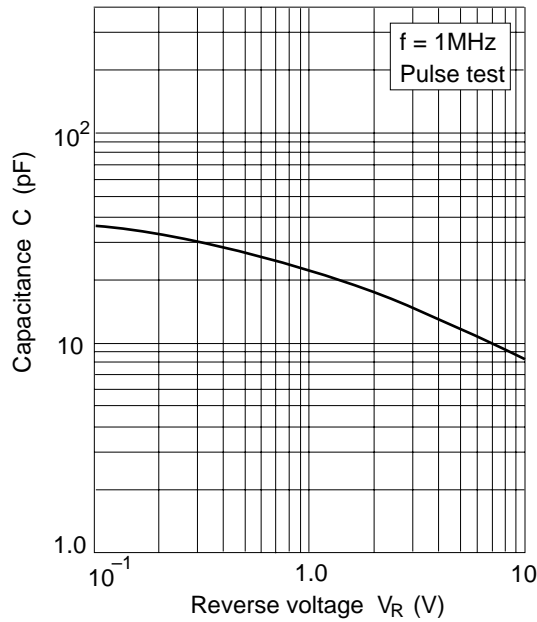
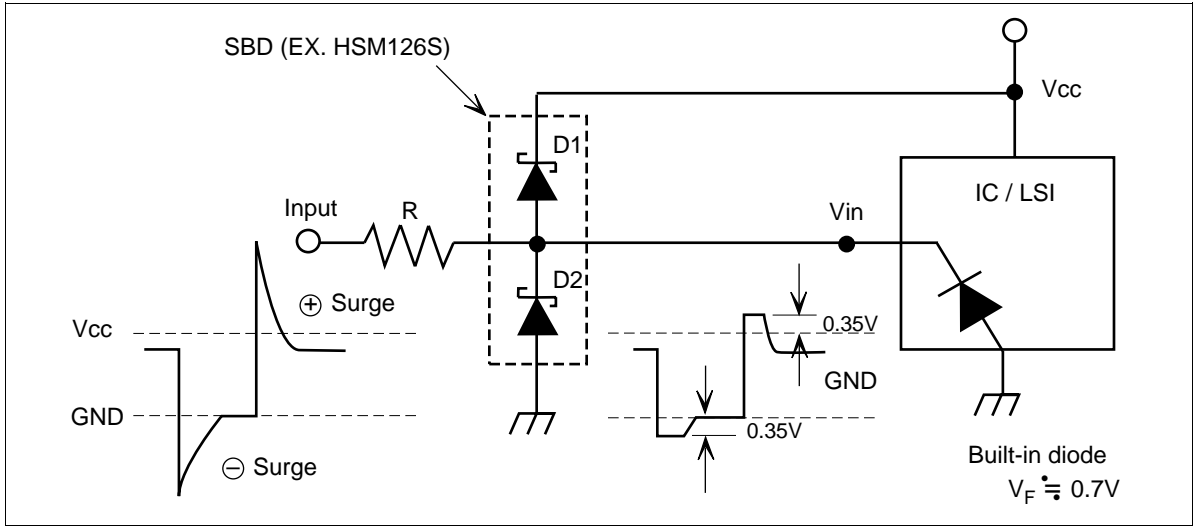


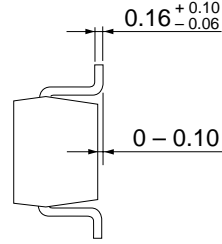
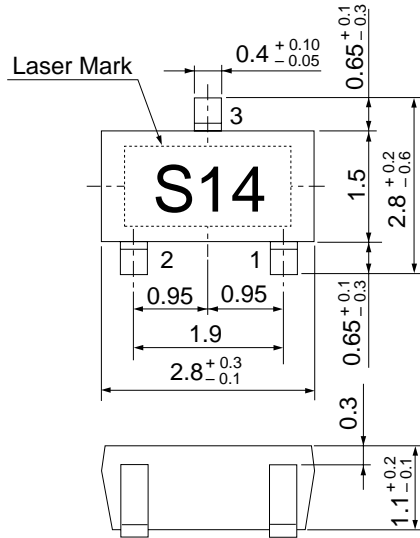
Fig.3 Capacitance Vs. Reverse voltage

Example of application circuit



Package Dimensions

Unit: mm



- 1 Cathode 2
- 2 Anode 1
- 3 Cathode 1
Anode 2

HITACHI Code	MPAK(1)
JEDEC Code	—
EIAJ Code	SC-59A
Weight (g)	0.011

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